



2N2484HR

Hi-Rel NPN bipolar transistor 60 V - 50 mA

Features

Parameter	Value
BV_{CEO}	60 V
I_C (max)	50 mA
h_{FE} at 10 V - 150 mA	> 250
Operating temperature range	- 65 °C to + 200 °C

- Linear gain characteristics
- Hermetic packages
- ESCC qualified
- European preferred part list - EPPL

Description

The 2N2484HR is a silicon planar epitaxial NPN transistor specifically designed for aerospace Hi-Rel applications and housed in hermetic packages. It complies with the ESCC 5000 qualification standard. It is ESCC qualified according to the 5201-001 specification. In case of conflict between this datasheet and ESCC detailed specification, the latter prevails.

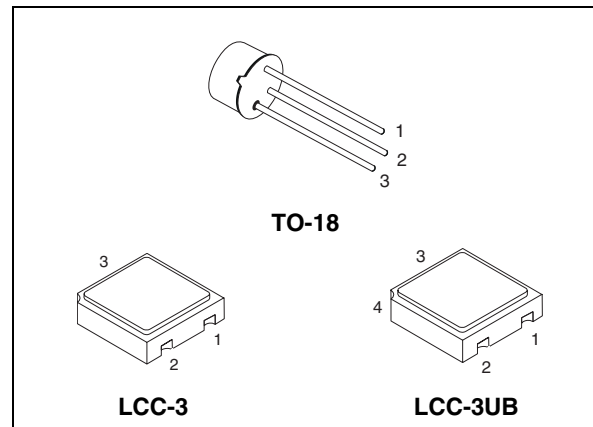
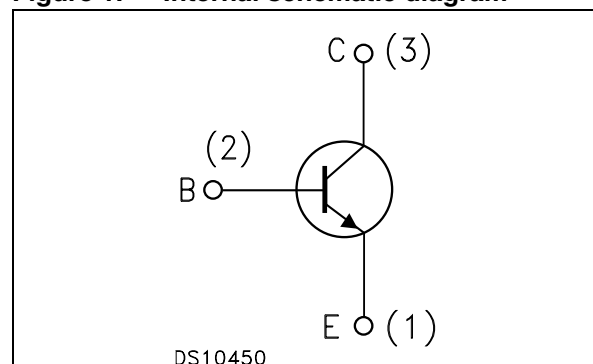


Figure 1. Internal schematic diagram



Pin 4 in LCC-3UB connected to the lid (for ground contact)

Table 1. Device summary

Order codes	ESCC Part number	Quality Level	Packages	Lead Finish	Mass (g)	EPPL
2N2484UB1	-	Engineering Model	LCC-3UB	Gold	0.06	-
2N2484UB06	5201/001/06	ESCC Flight	LCC-3UB	Gold	0.06	-
2N2484UB07	5201/001/07	ESCC Flight	LCC-3UB	Solder Dip	0.06	-
SOC2484	-	Engineering Model	LCC-3	Gold	0.06	-
SOC2484HRB	5201/001/01 or 02	ESCC Flight	LCC-3	Gold / Solder Dip ⁽¹⁾	0.06	-
2N2484HR	5201/001/04 or 05	ESCC Flight	TO-18	Gold / Solder Dip ⁽¹⁾	0.40	Y

1. Depending ESCC part number mentioned on the purchase order.

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-base voltage ($I_E = 0$)	60	V
V_{CEO}	Collector-emitter voltage ($I_B = 0$)	60	V
V_{EBO}	Emitter-base voltage ($I_C = 0$)	6	V
I_C	Collector current	50	mA
P_{TOT}	Total dissipation at $T_{amb} \leq 25\text{ °C}$ 2N2484HR	0.36	W
	2N2484UB1 / SOC2484HRB	0.36	W
	2N2484UB1 / SOC2484HRB ⁽¹⁾	0.73	W
	Total dissipation at $T_c \leq 25\text{ °C}$ for 2N2484HR	1.2	W
T_{STG}	Storage temperature	- 65 to 200	°C
T_J	Max. operating junction temperature	200	°C

1. When mounted on a 15 x 15 x 0.6 mm ceramic substrate.

Table 3. Thermal data for through-hole package

Symbol	Parameter	TO-18	Unit
R_{thJC}	Thermal resistance junction-case max	146	°C/W
R_{thJA}	Thermal resistance junction-ambient max	486	°C/W

Table 4. Thermal data for SMD package

Symbol	Parameter	LCC-3 / LCC-3UB	Unit
R_{thJA}	Thermal resistance junction-ambient max	486	°C/W
	Thermal resistance junction-ambient ⁽¹⁾ max	239	

1. When mounted on a 15 x 15 x 0.6 mm ceramic substrate.

2 Electrical characteristics

$T_{\text{case}} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Table 5. Electrical characteristics

Symbol	Parameter	Test conditions ⁽¹⁾	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CBO}}$	Collector-base breakdown voltage	$I_{\text{C}} = 10\text{ }\mu\text{A}$	60	-		V
$V_{(\text{BR})\text{CEO}}^{(2)}$	Collector-emitter breakdown voltage	$I_{\text{C}} = 10\text{ mA}$	60	-		V
$V_{(\text{BR})\text{EBO}}$	Emitter-base breakdown voltage	$I_{\text{E}} = 10\text{ }\mu\text{A}$	6	-		V
I_{CBO}	Collector-base cut-off current	$V_{\text{CB}} = 45\text{ V}$		-	10	nA
I_{CBO}	Emitter-base cut-off current	$V_{\text{EB}} = 5\text{ V}$		-	10	nA
$V_{\text{CE}(\text{SAT})}^{(2)}$	Collector-emitter saturation voltage	$I_{\text{C}} = 1\text{ mA}$ $I_{\text{B}} = 0.1\text{ mA}$		-	0.35	V
$h_{\text{FE}}^{(2)}$	DC forward current transfer ratio	$I_{\text{C}} = 1\text{ }\mu\text{A}$ $V_{\text{CE}} = 5\text{ V}$	30			
		$I_{\text{C}} = 10\text{ }\mu\text{A}$ $V_{\text{CE}} = 5\text{ V}$	100		500	
		$I_{\text{C}} = 100\text{ }\mu\text{A}$ $V_{\text{CE}} = 5\text{ V}$	175	-	550	
		$I_{\text{C}} = 1\text{ mA}$ $V_{\text{CE}} = 5\text{ V}$	250		650	
		$I_{\text{C}} = 10\text{ mA}$ $V_{\text{CE}} = 5\text{ V}$			800	
h_{fe}	High frequency current Gain 1	$V_{\text{CE}} = 5\text{ V}$ $I_{\text{C}} = 50\text{ }\mu\text{A}$ $f = 5\text{ MHz}$	3	-		
	High frequency current Gain 2	$V_{\text{CE}} = 5\text{ V}$ $I_{\text{C}} = 500\text{ }\mu\text{A}$ $f = 30\text{ MHz}$	2	-		
C_{obo}	Output capacitance	$V_{\text{CB}} = 5\text{ V}$ $I_{\text{E}} = 0$ $f = 1\text{ MHz}$		-	6	pF
C_{ibo}	Input capacitance	$V_{\text{EB}} = 0.5\text{ V}$ $I_{\text{C}} = 0$ $f = 1\text{ MHz}$		-	6	pF
h_{FE}	Small signal current gain	$I_{\text{C}} = 1\text{ mA}$ $V_{\text{CE}} = 5\text{ V}$ $f = 1\text{ kHz}$	150	-	900	
h_{ie}	Small signal input impedance	$I_{\text{C}} = 1\text{ mA}$ $V_{\text{CE}} = 5\text{ V}$ $f = 1\text{ kHz}$	3.5	-	24	k Ω
h_{oc}	Small signal output impedance	$I_{\text{C}} = 1\text{ mA}$ $V_{\text{CE}} = 5\text{ V}$ $f = 1\text{ kHz}$		-	40	μmho
h_{re}	Small signal reverse voltage transfer ratio	$I_{\text{C}} = 1\text{ mA}$ $V_{\text{CE}} = 5\text{ V}$ $f = 1\text{ kHz}$		-	800	10^{-6}
N_{FW}	Wide-Band noise	$V_{\text{CE}} = 5\text{ V}$ $I_{\text{C}} = 10\text{ }\mu\text{A}$ $R_{\text{S}} = 10\text{ k}\Omega$		-	3	dB

Electrical characteristics

2N2484HR

Table 5. Electrical characteristics

Symbol	Parameter	Test conditions (1)	Min.	Typ.	Max.	Unit
NF_{N1}	Spot noise figure	$V_{CE} = 5\text{ V}$ $I_C = 10\ \mu\text{A}$ $R_S = 10\ \text{k}\Omega$ $f = 100\ \text{Hz}$ Power BW = 200 Hz		-	3	dB
NF_{N2}		$V_{CE} = 5\text{ V}$ $I_C = 10\ \mu\text{A}$ $R_S = 10\ \text{k}\Omega$ $f = 1\ \text{kHz}$ Power BW = 20 Hz		-	10	
NF_{N3}		$V_{CE} = 5\text{ V}$ $I_C = 10\ \mu\text{A}$ $R_S = 10\ \text{k}\Omega$ $f = 10\ \text{kHz}$ Power BW = 2 Hz		-	2	

1. Measurement performed on a sample basis, LTPD 7 or less.
2. Pulse measurement: Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 1.0\ \%$

Table 6. Electrical characteristics at high and low temperatures

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{CBO}	Collector-base cut-off current	$V_{CB} = 45\text{ V}$ $T_{amb} = 150\ ^\circ\text{C}$		-	10	μA
h_{FE2}	DC forward current transfer ratio	$I_C = 10\ \mu\text{A}$ $V_{CE} = 5\text{ V}$ $T_{amb} = -55\ ^\circ\text{C}$	20	-		

3 Test circuit

Figure 2. Circuit for electrical measurements

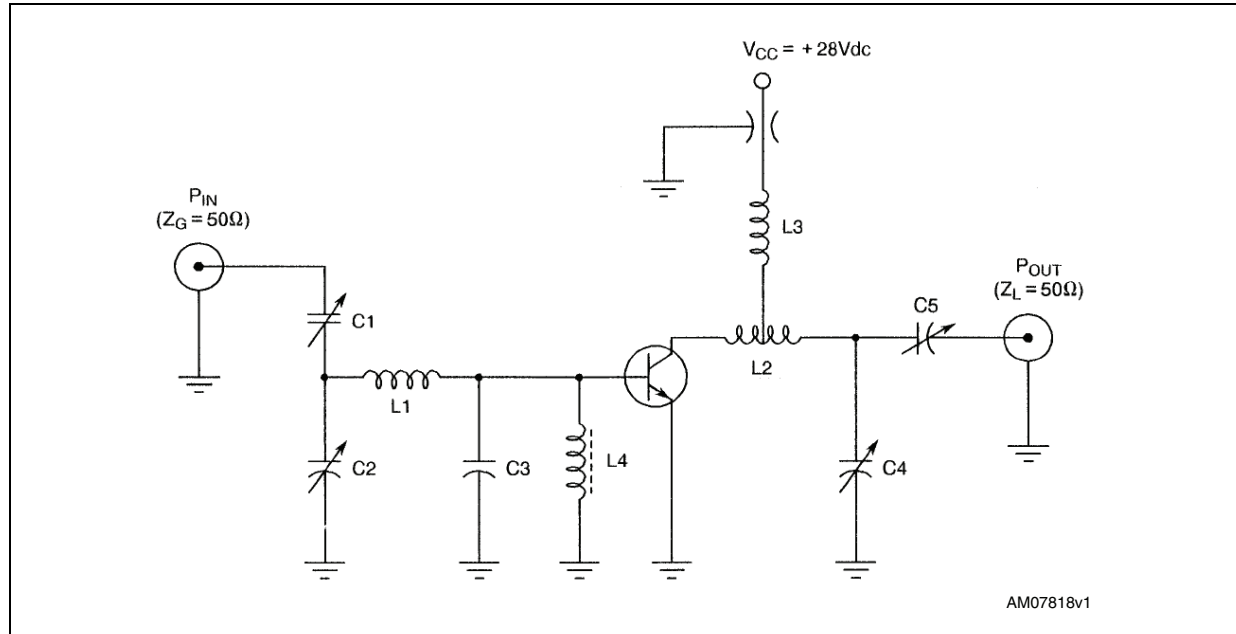


Table 7. List of components

Component	Description
C1, C2, C5	3.0 - 35 pF
C3 ⁽¹⁾	24 pF
C4	0.4 - 7.0 pF
L1	Straight piece n° 16 bare tin wire, 5/8 inch long
L2	3 turns n° 16 wire, 1/4 inch ID, 5/16 inch long
L3	1 turn n° 18 wire, 1/4 inch ID, 1/4 inch long
L4	Ferrite rf choke, Z = 450 Ω

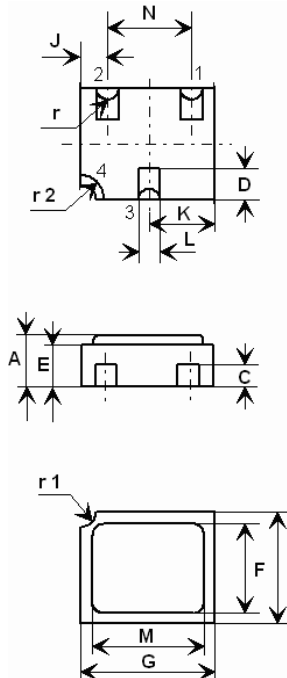
1. For optimum performance, C3 should be mounted as close as possible to the base lead.

4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

LCC-3UB mechanical data

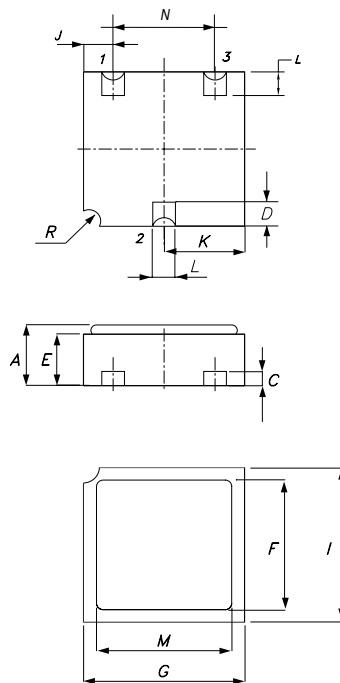
Dim.	mm.		
	Min.	Typ.	Max.
A	1.16		1.42
C	0.46	0.51	0.56
D	0.56	0.76	0.96
E	0.92	1.02	1.12
F	1.95	2.03	2.11
G	2.92	3.05	3.18
I	2.41	2.54	2.67
J	0.42	0.57	0.72
K	1.37	1.52	1.67
L	0.41	0.51	0.61
M	2.46	2.54	2.62
N	1.81	1.91	2.01
r		0.20	
r1		0.30	
r2		0.56	



8206487

LCC-3 mechanical data

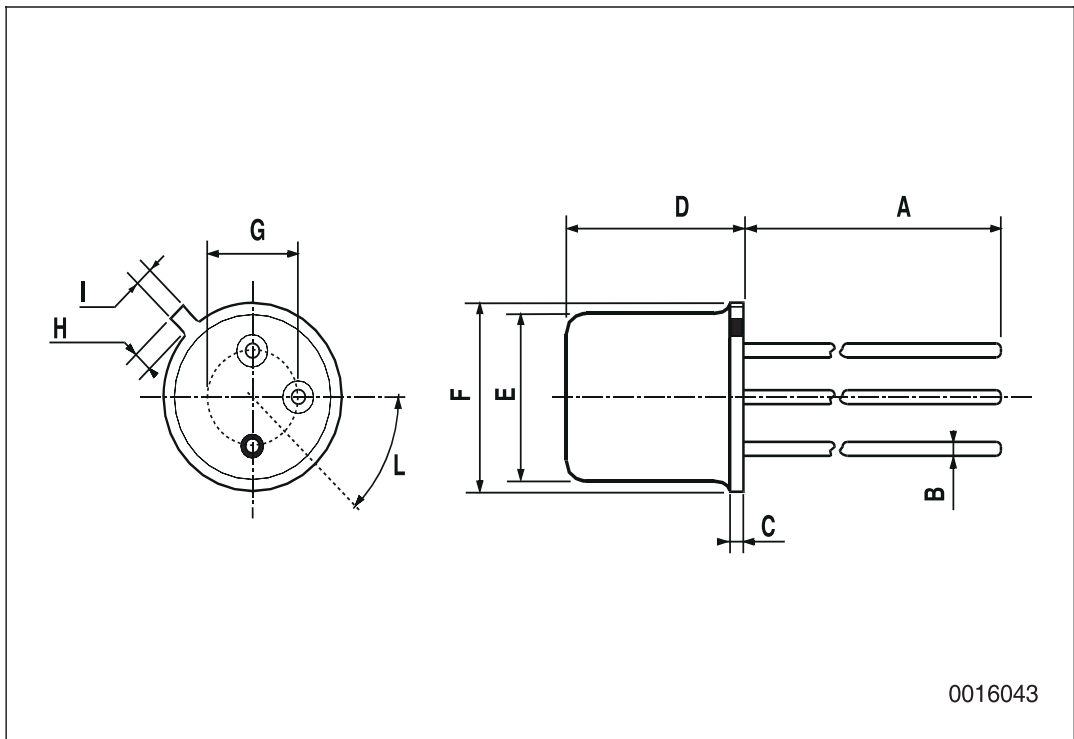
Dim.	mm.		
	Min.	Typ.	Max.
A	1.16		1.42
C	0.45	0.50	0.56
D	0.60	0.76	0.91
E	0.91	1.01	1.12
F	1.95	2.03	2.11
G	2.92	3.05	3.17
I	2.41	2.54	2.66
J	0.42	0.57	0.72
K	1.37	1.52	1.67
L	0.40	0.50	0.60
M	2.46	2.54	2.62
N	1.80	1.90	2.00
R		0.30	



0041211

TO-18 Mechanical data

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A		12.7			0.500	
B			0.49			0.019
D			5.3			0.208
E			4.9			0.193
F			5.8			0.228
G	2.54			0.100		
H			1.2			0.047
I			1.16			0.045
L	45°			45°		



5 Order codes

Table 8. Order codes

Order codes	ESCC Part number	Packages	Lead Finish	Marking	EPPL	Packing
2N2484UB1	-	LCC-3UB	Gold	2N2484UB1	-	Waffle pack
2N2484UB06	5201/001/06	LCC-3UB	Gold	520100106	-	Waffle pack
2N2484UB07	5201/001/07	LCC-3UB	Solder Dip	520100107	-	Waffle pack
SOC2484	-	LCC-3	Gold	SOC2484	-	Waffle pack
SOC2484HRB	5201/001/01 or 02	LCC-3	Gold or Solder Dip ⁽¹⁾	520100101 or 02	-	Waffle pack
2N2484HR	5201/001/04 or 05	TO-18	Gold or Solder Dip ⁽¹⁾	520100104 or 05	Y	Strip pack

1. Depending ESCC part number mentioned on the purchase order.

Contact ST sales office for information about the specific conditions for:

- Products in die form
- Tape & reel packing

6 Revision history

Table 9. Document revision history

Date	Revision	Changes
09-Jul-2010	1	Initial release

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